

## 20V N-Channel Enhancement Mode MOSFET

### DESCRIPTION

The STN2302 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density. advanced trench technology to provide excellent  $R_{DS(ON)}$ . low gate charge and operation gate as 1.8V. This device is suitable for use as a load switch or other general applications.

*STN2302S-TRG ROHS Compliant This is Halogen Free*

### FEATURE

- ◆ 20V/4.0A,  $R_{DS(ON)} = 50m\Omega(typ.)@V_{GS} = 4.5V$
- ◆ 20V/3.0A,  $R_{DS(ON)} = 65m\Omega(typ.)@V_{GS} = 2.5V$
- ◆ Super high density cell design for extremely low Gate Charge
- ◆ Exceptional on-resistance and Maximum DC current capability

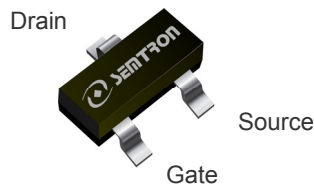
### APPLICATIONS

- ◆ Power Management in Note book
- ◆ Portable Equipment
- ◆ Load Switch

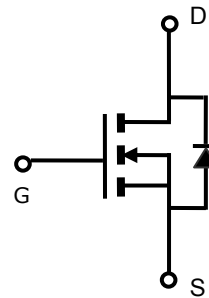


N-Channel Enhancement Mode MOSFET

### PIN CONFIGURATION



SOT-23  
Top View



### PART NUMBER INFORMATION

<b>ST N 2302 S - TR G</b> a b c d e f	a : Company name. b : Channel type. c : Product Serial number. d : Package code e : Handling code f : Green product code
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## ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
STN2302S-TRG	S : SOT-23	TR : Tape&Reel	3K/Reel

- ※ Year Code : 0 ~ 9, 2010 : 0
- ※ Week Code : A(1~2) ~ Z(53~54)
- ※ SOT-23 : Only available in tape and reel packaging.

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C Unless otherwise noted )

Symbol	Parameter	Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage	20	V
V <sub>GSS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub>	Continuous Drain Current (T <sub>C</sub> =25°C) <sup>A</sup>	V <sub>GS</sub> =4.5V	4.6
	Continuous Drain Current (T <sub>C</sub> =70°C) <sup>A</sup>		3.8
I <sub>DM</sub>	Pulsed Drain Current <sup>B</sup>	14	A
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> =25°C	1.0
		T <sub>A</sub> =70°C	0.7
T <sub>J</sub>	Operation Junction Temperature	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.  
 Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## THERMAL DATA

Symbol	Parameter	Typ	Max	Unit	
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient <sup>A</sup>	Steady-State	-	125	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Lead <sup>A</sup>	Steady-State	-	85	°C/W

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5		1.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =20V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			5	
R <sub>DS(ON)</sub>	Drain-source On-Resistance <sup>B</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.0A V <sub>GS</sub> =2.5V, I <sub>D</sub> =3.0A		40 54	50 75	mΩ
G <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =3A		10.5		S
<b>Source-Drain Diode</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V		0.7	1.2	V
I <sub>S</sub>	Continuous Source Current <sup>AD</sup>				3.6	A
<b>Dynamic Parameters</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V V <sub>GS</sub> =4.5V I <sub>D</sub> =3.0A		4.7	6.6	nC
Q <sub>gs</sub>	Gate-Source Charge			0.68	0.96	
Q <sub>gd</sub>	Gate-Drain Charge			1.3	1.8	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1MHz		296	415	pF
C <sub>oss</sub>	Output Capacitance			44	62	
C <sub>rss</sub>	Reverse Transfer Capacitance			35	49	
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =10V I <sub>D</sub> =3.0A V <sub>GEN</sub> =4.5V R <sub>G</sub> =3.3Ω		1.4	2.8	nS
t <sub>r</sub>				40	72	
t <sub>d(off)</sub>	Turn-Off Time			12.4	25	
t <sub>f</sub>				5.6	11	

Note:

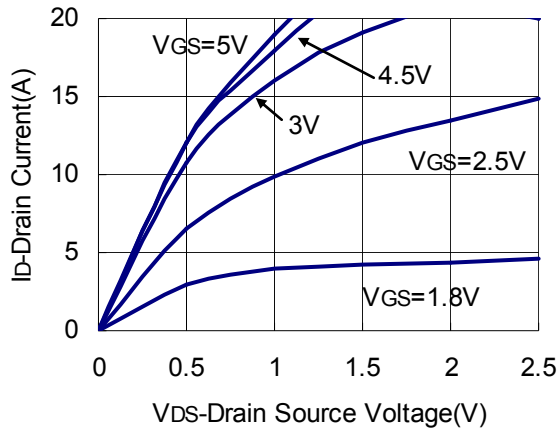
- The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.
- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=-25V, V<sub>GS</sub>=-10V, L=0.1mH.
- The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

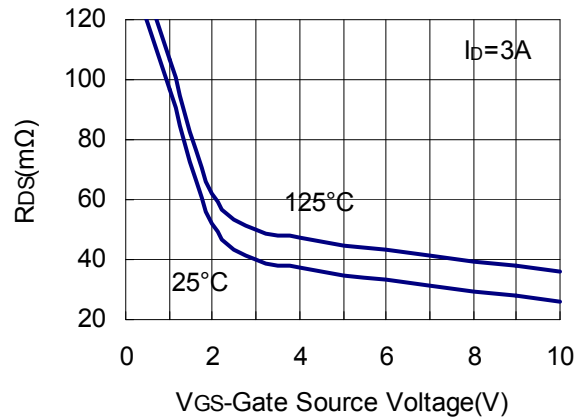
We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.

## TYPICAL CHARACTERISTICS

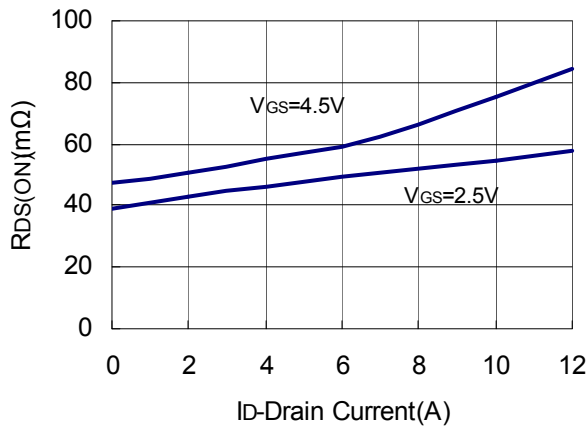
**Output Characteristics**



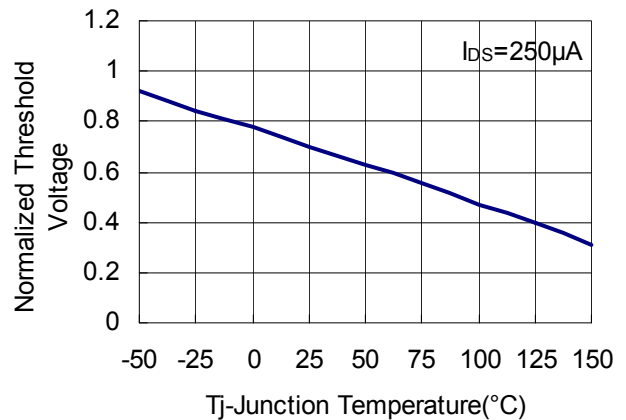
**Drain-Source On Resistance**



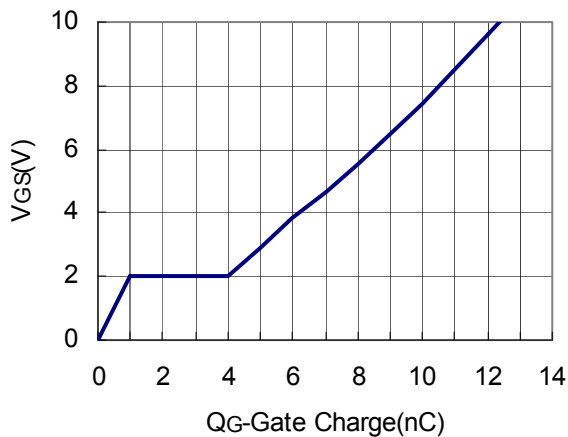
**Drain Source On Resistance**



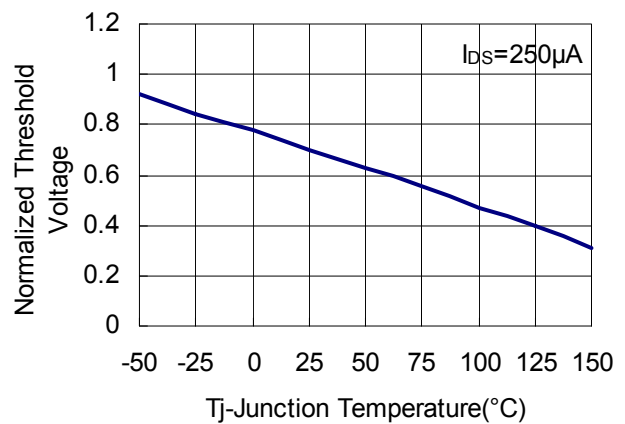
**Gate Threshold Voltage**



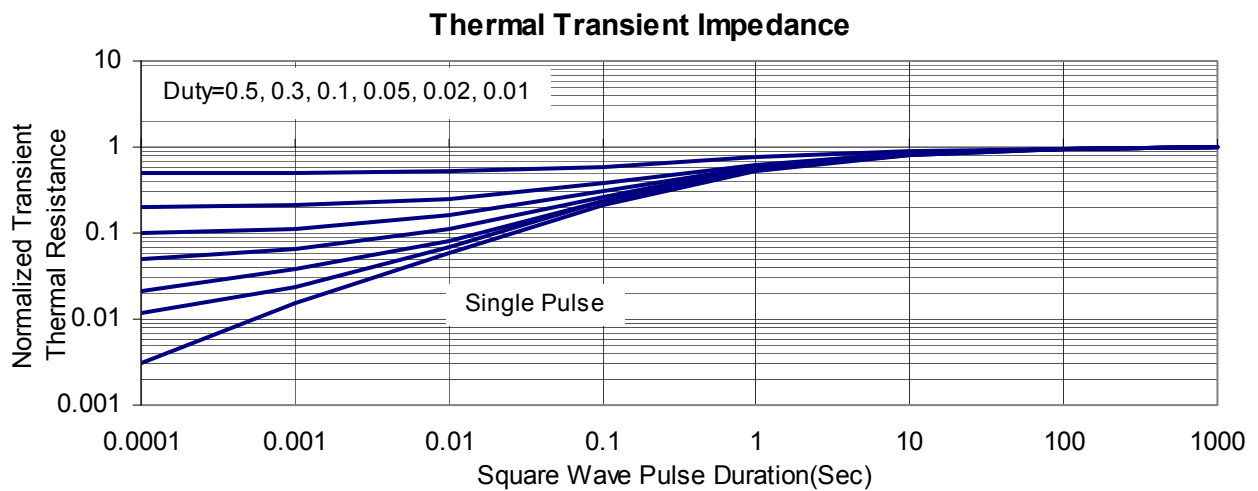
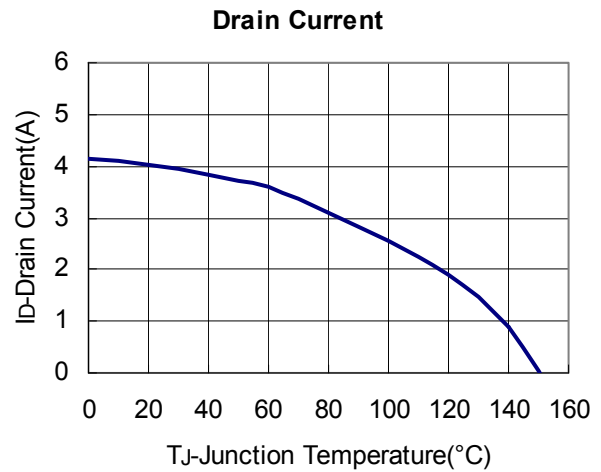
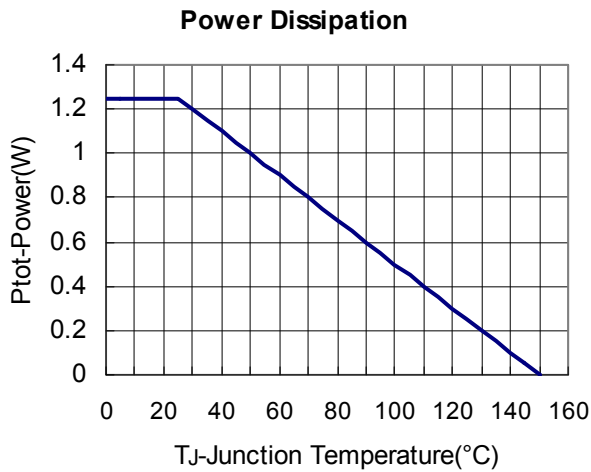
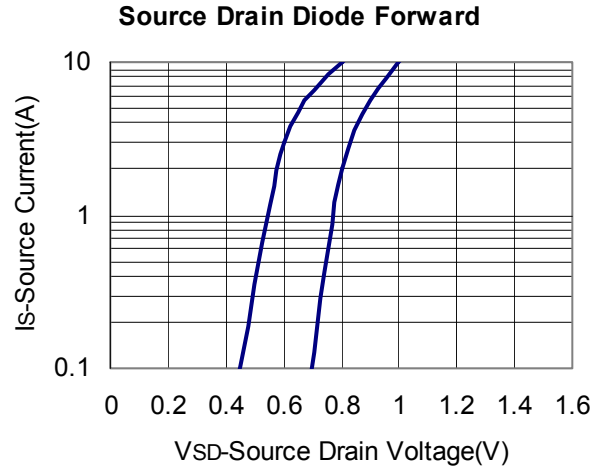
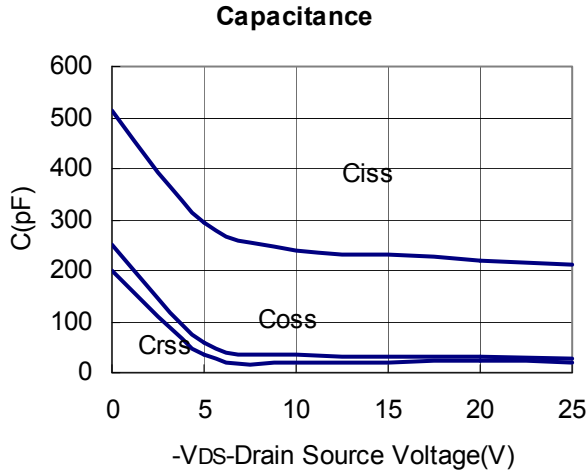
**Gate Charge**



**Gate Threshold Voltage**



## TYPICAL CHARACTERISTICS



## SOT-23 PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L1	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°

